



Revision History

| Revision | Date | Description |
|----------|------------|--|
| 1.9 | Oct 2009 | <ul style="list-style-type: none">Updated section 5.1, table 2. |
| 1.8 | Aug 2009 | <ul style="list-style-type: none">Updated section 5.2, table 3. |
| 1.7 | Oct 2005 | <ul style="list-style-type: none">Changed interrupt signals INTA# and INTB# symbol types from TS (tri-state) to OD (open drain). |
| 1.6 | June 2005 | <ul style="list-style-type: none">Added a more detailed AUX_PWR pin description.Added tristate and XOR non-JTAG test modes description. |
| 1.5 | April 2005 | <ul style="list-style-type: none">Added lead-free product and ordering information.Added major product features to cover page.Added text stating that the TTL inputs on the Ethernet controller are not 5V tolerant.Updated thermal specifications. |
| 1.4 | Sept 2004 | Corrected the nominal impedance values for the I/O cells from 50 K Ω to a nominal impedance value of 120 K Ω , with a minimum of 90 K Ω and a maximum of 190 K Ω . |
| 1.3 | Dec 2003 | Added an I/O Characteristics table in Section 4.3, "DC Characteristics." |
| 1.2 | Nov 2003 | Corrected typing error of "q" to "0" in Section 6.3, "Thermal Specifications," on page 38. |
| 1.1 | Sept 2003 | Declassified document from confidential status. |
| 1.0 | July 2003 | Initial release. |

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1.0 Introduction

The Intel® 82546GB Dual Port Gigabit Ethernet Controller is a single, compact component with two full integrated Gigabit Ethernet Media Access Control (MAC) and physical layer (PHY) functions. The Intel® 82546GB enables dual port Gigabit Ethernet implementations in a very small area and can be used for desktop and workstation PC network designs as well as backplane applications with critical space constraints.

The Intel® 82546GB integrates Intel's fourth generation gigabit MAC and PHY to provide a standard IEEE 802.3 Ethernet interface for 1000BASE-T, 100BASE-TX, and 10BASE-T applications (802.3, 802.3u, and 802.3ab). The controller is capable of transmitting and receiving two channels of data at rates of 1000 Mbps, 100 Mbps, or 10 Mbps. In addition, it provides a 64-bit wide direct Peripheral Component Interconnect (PCI) 2.3 and PCI-X 1.0a compliant interface capable of operating at frequencies up to 133 MHz. The 82546GB also delivers a dual port PCI-X solution without added bridge latency.

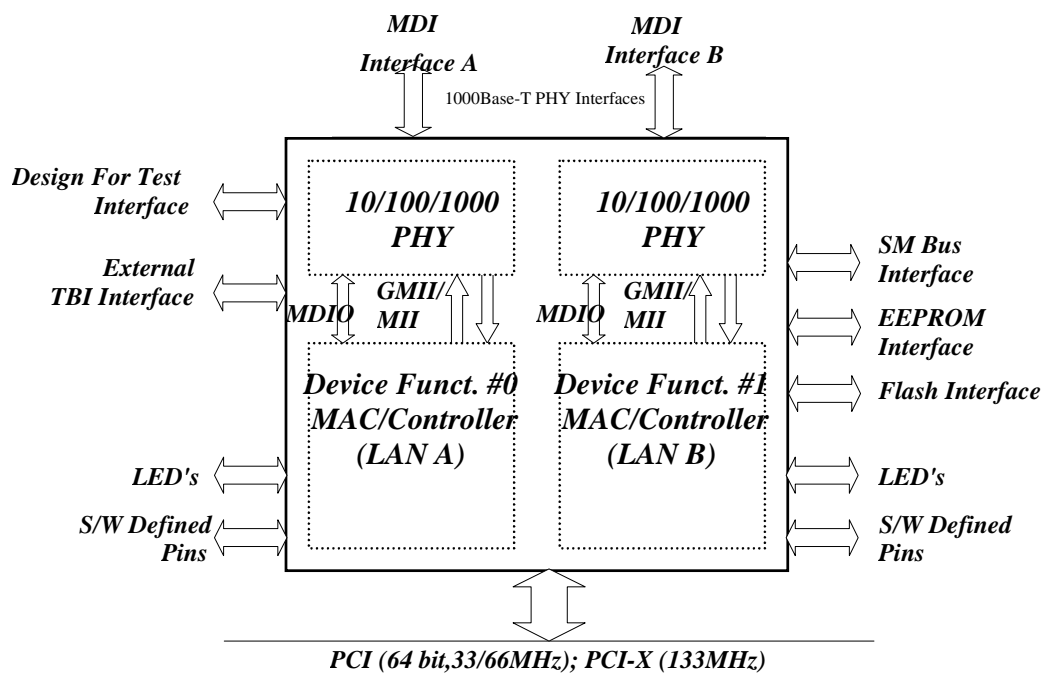
The Intel® 82546GB on-board System Management Bus (SMB) port enables network manageability implementations required by information technology personnel for remote control and alerting through the LAN. Using the SMB, management packets can be routed to or from a management processor. The SMB port enables industry standards, such as Intelligent Platform Management Interface (IPMI) and Alert Standard Format (ASF), to be implemented using the 82546GB. In addition, on chip ASF 1.0 circuitry provides alerting and remote control capabilities with standardized interfaces.

The 82546GB Dual Port Gigabit Ethernet Controller architecture is designed to deliver high performance and PCI/PCI-X bus efficiency. Wide internal data paths eliminate performance bottlenecks by efficiently handling large address and data words. Combining a parallel and pipelined logic architecture optimized for Gigabit Ethernet and independent transmit and receive queues, the 82546GB controller efficiently handles packets with minimum latency. The 82546GB controller includes advanced interrupt handling features to limit PCI bus traffic and a PCI interface that maximizes the use of bursts for efficient bus usage. The 82546GB is able to cache up to 64 packet descriptors in a single burst for efficient PCI bandwidth use. A large 64 Kbyte on-chip packet buffer maintains superior performance as available PCI bandwidth changes. By using hardware acceleration, the controller is able to offload tasks, such as checksum calculations and TCP segmentation, from the host processor.



The 82546GB is packaged in a 21 mm x 21 mm 364-ball grid array and footprint compatible with the Intel® 82544GC Gigabit Ethernet Controller and 82546EB Dual Port Gigabit Ethernet Controller.

Figure 1. Gigabit Ethernet Controller Block Diagram



1.1 Document Scope

This document contains datasheet specifications for the 82546GB Dual Port Gigabit Ethernet Controller, which includes signal descriptions, DC and AC parameters, packaging data, and pinout information.

1.2 Reference Documents

It is assumed that the designer is acquainted with high-speed design and board layout techniques. Document that may provide additional information are:

- PCI Local Bus Specification, Revision 2.3, PCI Special Interest Group.
- PCI-X Specification, Revision 1.0a, PCI Special Interest Group.
- PCI Bus Power Management Interface Specification, Rev. 1.1, PCI Special Interest Group.
- IEEE Standard 802.3, 1996 Edition, Institute of Electrical and Electronics Engineers (IEEE).
- IEEE Standard 802.3u, 1995 Edition, Institute of Electrical and Electronics Engineers (IEEE).
- IEEE Standard 802.3x, 1997 Edition, Institute of Electrical and Electronics Engineers (IEEE).
- IEEE Standard 802.3z, 1998 Edition, Institute of Electrical and Electronics Engineers (IEEE).



- IEEE Standard 802.3ab, 1999 Edition, Institute of Electrical and Electronics Engineers (IEEE).
- Intel® Ethernet Controllers Timing Device Selection Guide, AP-419. Intel Corporation.

1.3 Product Codes

The product ordering code for the 82546GB is: FW82546GB.

The lead-free product ordering code for the 82546GB is: NH82546GB.



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2.0 Additional 82546GB Features

2.1 PCI

| Feature | Benefits |
|--|--|
| Algorithms that optimally use advanced PCI, MWI, MRM, and MRL commands as well as PCI-X MRD, MRB, and MWB commands | <ul style="list-style-type: none">• Efficient bus operations |

2.2 MAC

| Features | Benefits |
|--|---|
| Low-latency transmit and receive queues | <ul style="list-style-type: none">• Network packets handled without waiting or buffer overflow. |
| Caches up to 64 packet descriptors in a single burst | <ul style="list-style-type: none">• Efficient use of PCI bandwidth |
| Descriptor ring management hardware for transmit and receive | <ul style="list-style-type: none">• Simple software programming model |
| Mechanism available for reducing interrupts generated by transmit and receive operations | <ul style="list-style-type: none">• Maximizes system performance and throughput |
| Support for transmission and reception of packets up to 16 Kbytes | <ul style="list-style-type: none">• Enables jumbo frames |

2.3 PHY

| Feature | Benefits |
|--|--|
| State-of-the-art DSP architecture implements digital adaptive equalization, echo cancellation, and cross-talk cancellation | <ul style="list-style-type: none">• Robust performance in noisy environments• Tolerance of common electrical signal impairments |



2.4 Host Offloading

| Features | Benefits |
|--|--|
| Descriptor ring management hardware for transmit and receive | <ul style="list-style-type: none"> Optimized fetching and write-back mechanisms for efficient system memory and PCI bandwidth usage |
| 16-Kbyte jumbo frame support | <ul style="list-style-type: none"> High throughput for large data transfers on networks supporting jumbo frames |
| Interrupt coalescing (multiple packets per interrupt) | <ul style="list-style-type: none"> Increased throughput by reducing interrupts generated by transmit and receive operations |

2.5 Manageability

| Features | Benefits |
|--|--|
| On-board SMB port | <ul style="list-style-type: none"> Enables IPMI and ASF implementations Allows packets routing to and from either LAN port and a server management processor |
| Preboot eXecution Environment (PXE) Flash interface support (32-bit and 64-bit) | <ul style="list-style-type: none"> Local Flash interface for PXE image |
| Compliance with PCI Power Management 1.1 and ACPI 2.0 register set compliant including: <ul style="list-style-type: none"> D0 and D3 power states Network Device Class Power Management Specification 1.1 PCI Specification 2.3 | <ul style="list-style-type: none"> PCI power management capability requirements for PC and embedded applications |
| SNMP and RMON statistic counters | <ul style="list-style-type: none"> Easy system monitoring with industry standard consoles |
| SDG 3.0, WfM 2.0, and PC2001 compliance | <ul style="list-style-type: none"> Remote network management capabilities through DMI 2.0 and SNMP software |
| Wake on LAN support | <ul style="list-style-type: none"> Packet recognition and wake-up for NIC and LOM applications without software configuration |
| IPMI MAC Address Read capability | <ul style="list-style-type: none"> Allows MAC address read to be read by remote users through IMPI |
| IPMI I ² C Addressing capability | <ul style="list-style-type: none"> Enables device addressing over the I²C bus |



2.6 Device

| Features | Benefits |
|---|--|
| Internal PLL for clock generation (use either a 25 MHz crystal or a 25 MHz oscillator) | <ul style="list-style-type: none">• Lower component count and system cost |
| JTAG (IEEE 1149.1) Test Access Port built in silicon | <ul style="list-style-type: none">• Simplified testing using boundary scan |
| On-chip power control circuitry | <ul style="list-style-type: none">• Reduced number of on-board power supply regulators• Simplified power supply design |
| Eight software definable pins | <ul style="list-style-type: none">• Additional flexibility for LEDs or other low speed I/O devices |
| Supports little endian byte ordering for both 32 and 64 bit systems and big endian byte ordering for 64 bit systems | <ul style="list-style-type: none">• Portable across application architectures |
| Provides loopback capabilities | <ul style="list-style-type: none">• Validates silicon integrity |
| Single-pin LAN disable function | <ul style="list-style-type: none">• Allows LAN port enabling and disabling through BIOS control (OS not required) for both ports |
| VLAN Management Filtering | <ul style="list-style-type: none">• Allows VLAN-based management packet filtering |
| Full 2/3 Wire Downshift capability | <ul style="list-style-type: none">• Allows silicon to downshift speed to two or three wire install and still achieve valid link |
| PICMIG 3.1 Compliant SERDES Interface | <ul style="list-style-type: none">• Enables interface connections with PICMIG 3.1 compliant devices |

2.7 Technology

| Features | Benefits |
|--|--|
| 364-pin Ball Grid Array (BGA) package | <ul style="list-style-type: none">• 21 mm x 21 mm component makes LOM designs easier |
| Footprint compatible with the 82544GC/EI and 82545GM/EM single port gigabit Ethernet controllers | <ul style="list-style-type: none">• Single port or dual port implementation on the same board with minor option changes. |
| Implemented in 0.15µ CMOS process | <ul style="list-style-type: none">• Offers lowest geometry to minimize power and size while maintaining Intel quality reliability standards |
| 3.3 V PCI signaling with an average power dissipation of 3.5 W | <ul style="list-style-type: none">• Lower power requirements |
| Operating temperature: 0° C to 55° C (with or without thermal management, maximum); 0° C to 70° C (with increased thermal management, maximum) | <ul style="list-style-type: none">• Extended temperature attainable with thermal management device for more demanding systems requiring a wider temperature range. |



3.0 Signal Descriptions

Note: The targeted signal names are subject to change without notice. Verify with your local Intel sales office that you have the latest information before finalizing a design.

3.1 Signal Type Definitions

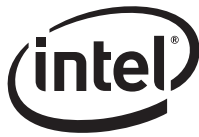
The signals of the 82546GB controller are electrically defined as follows:

| Name | Definition |
|------|---|
| I | Input. Standard input only digital signal. |
| O | Output. Standard output only digital signal. |
| TS | Tri-state. Bi-directional three-state digital input/output signal. |
| STS | Sustained Tri-state. Sustained digital three-state signal driven by one agent at a time. An agent driving the STS pin low must actively drive it high for at least one clock before letting it float. The next agent of the signal cannot drive the pin earlier than one clock after it has been released by the previous agent. |
| OD | Open Drain. Wired-OR with other agents. The signaling agent asserts the OD signal, but the signal is returned to the inactive state by a weak pull-up resistor. The pull-up resistor may require two or three clock periods to fully restore the signal to the de-asserted state. |
| A | Analog. PHY analog data signal. |
| P | Power. Power connection, voltage reference, or other reference connection. |
| R | Reserved. |

Note: The TTL inputs on the Ethernet controller are not 5V tolerant. If these inputs are connected to 5V, then damage to the Ethernet controller is likely to occur. TTL inputs include the JTAG interface pins, the FLASH interface pins, the EEPROM interface pins, the LED pins, the software definable pins, and the LAN_PWR_GOOD pin.

3.2 PCI Bus Interface

When the Reset signal (RST#) is asserted, the 82546GB will not drive any PCI output or bi-directional pins except the Power Management Event signal (PME#).



3.2.1 PCI Address, Data and Control Signals

| Symbol | Type | Name and Function |
|-----------|------|---|
| AD[63:0] | TS | <p>Address and Data. Address and data signals are multiplexed on the same PCI pins. A bus transaction includes an address phase followed by one or more data phases.</p> <p>The address phase is the clock cycle when the Frame signal (FRAME#) is asserted low. During the address phase AD[63:0] contain a physical address (64 bits). For I/O, this is a byte address, and for configuration and memory, a DWORD address. The 82546GB device uses little endian byte ordering.</p> <p>During data phases, AD[7:0] contain the least significant byte (LSB) and AD[63:56] contain the most significant byte (MSB).</p> <p>The 82546GB controller may optionally be connected to a 32-bit PCI bus. On the 32-bit bus, AD[63:32] and other signals corresponding to the high order byte lanes do not participate in the bus cycle.</p> |
| CBE[7:0]# | TS | <p>Bus Command and Byte Enables. Bus command and byte enable signals are multiplexed on the same PCI pins. During the address phase of a transaction, CBE[7:0]# define the bus command. In the data phase, CBE[7:0]# are used as byte enables. The byte enables are valid for the entire data phase and determine which byte lanes contain meaningful data.</p> <p>CBE0# applies to byte 0 (LSB) and CBE7# applies to byte 7 (MSB).</p> |
| PAR | TS | <p>Parity. The Parity signal is issued to implement even parity across AD[31:0] and CBE[3:0]#. PAR is stable and valid one clock after the address phase. During data phases, PAR is stable and valid one clock after either IRDY# is asserted on a write transaction or TRDY# is asserted after a read transaction. Once PAR is valid, it remains valid until one clock after the completion of the current data phase.</p> <p>When the 82546GB controller is a bus master, it drives PAR for address and write data phases, and as a slave device, drives PAR for read data phases.</p> |
| PAR64 | TS | <p>Parity 64. The Parity 64 signal is issued to implement even parity across AD[63:32] and CBE[7:4]#. PAR64 is stable and valid one clock after the address phase. During data phases, PAR64 is stable and valid one clock after either IRDY# is asserted on a write transaction or TRDY# is asserted after a read transaction. Once PAR64 is valid, it remains valid until one clock after the completion of the current data phase.</p> <p>When the 82546GB controller is a bus master, it drives PAR64 for address and write data phases, and as a slave device, drives PAR64 for read data phases.</p> |
| FRAME# | STS | <p>Cycle Frame. The Frame signal is driven by the 82546GB device to indicate the beginning and length of an access and indicate the beginning of a bus transaction. While FRAME# is asserted, data transfers continue. FRAME# is de-asserted when the transaction is in the final data phase.</p> |
| IRDY# | STS | <p>Initiator Ready. Initiator Ready indicates the ability of the 82546GB controller (as bus master device) to complete the current data phase of the transaction. IRDY# is used in conjunction with the Target Ready signal (TRDY#). The data phase is completed on any clock when both IRDY# and TRDY# are asserted.</p> <p>During the write cycle, IRDY# indicates that valid data is present on AD[63:0]. For a read cycle, it indicates the master is ready to accept data. Wait cycles are inserted until both IRDY# and TRDY# are asserted together. The 82546GB controller drives IRDY# when acting as a master and samples it when acting as a slave.</p> |
| TRDY# | STS | <p>Target Ready. The Target Ready signal indicates the ability of the 82546GB controller (as a selected device) to complete the current data phase of the transaction. TRDY# is used in conjunction with the Initiator Ready signal (IRDY#). A data phase is completed on any clock when both TRDY# and IRDY# are sampled asserted.</p> <p>During a read cycle, TRDY# indicates that valid data is present on AD[63:0]. For a write cycle, it indicates the target is ready to accept data. Wait cycles are inserted until both IRDY# and TRDY# are asserted together. The 82546GB device drives TRDY# when acting as a slave and samples it when acting as a master.</p> |



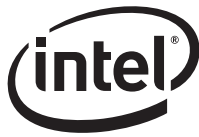
| Symbol | Type | Name and Function |
|---------|------|---|
| STOP# | STS | Stop. The Stop signal indicates the current target is requesting the master to stop the current transaction. As a slave, the 82546GB controller drives STOP# to request the bus master to stop the transaction. As a master, the 82546GB controller receives STOP# from the slave to stop the current transaction. |
| IDSEL# | I | Initialization Device Select. The Initialization Device Select signal is used by the 82546GB as a chip select signal during configuration read and write transactions. |
| DEVSEL# | STS | Device Select. When the Device Select signal is actively driven by the 82546GB, it signals notifies the bus master that it has decoded its address as the target of the current access. As an input, DEVSEL# indicates whether any device on the bus has been selected. |
| VIO | P | VIO. The VIO signal is a voltage reference for the PCI interface (3.3 V or 5 V PCI signaling environment). It is used as the clamping voltage. Note: An external resistor is required between the voltage reference and the VIO pin. The target resistor value is 100 K Ω |

3.2.2 Arbitration Signals

| Symbol | Type | Name and Function |
|--------|------|---|
| REQ64# | TS | Request Transfer. The Request Transfer signal is generated by the current initiator indicating its desire to perform a 64-bit transfer. REQ64# has the same timing as the Frame signal. |
| ACK64# | TS | Acknowledge Transfer. The Acknowledge Transfer signal is generated by the currently addressed target in response to the REQ64# assertion by the initiator. ACK64# has the same timing as the Device Select signal. |
| REQ# | TS | Request Bus. The Request Bus signal is used to request control of the bus from the arbiter. This signal is point-to-point. |
| GNT# | I | Grant Bus. The Grant Bus signal notifies the 82546GB that bus access has been granted. This is a point-to-point signal. |
| LOCK# | I | Lock Bus. The Lock Bus signal is asserted by an initiator to require sole access to a target memory device during two or more separate transfers. The 82546GB device does not implement bus locking. |

3.2.3 Interrupt Signals

| Symbol | Type | Name and Function |
|--------|------|--|
| INTA# | OD | Interrupt A. Interrupt A is used to request an interrupt by port 1 of the 82546GB. It is an active low, level-triggered interrupt signal. |
| INTB# | OD | Interrupt B. Interrupt B is used to request an interrupt by port 2 of the 82546GB. It is an active low, level-triggered interrupt signal. |



3.2.4 System Signals

| Symbol | Type | Name and Function |
|--------------|------|---|
| CLK | I | PCI Clock. The PCI Clock signal provides timing for all transactions on the PCI bus and is an input to the 82546GB device. All other PCI signals, except the Interrupt A (INTA#) and PCI Reset signal (RST#), are sampled on the rising edge of CLK. All other timing parameters are defined with respect to this edge. |
| M66EN | I | 66 MHz Enable. The 66 MHz Enable signal is used to indicate whether or not the system bus is capable of supporting an operating frequency of 66 MHz. |
| RST# | I | PCI Reset. When the PCI Reset signal is asserted, all PCI output signals, except the Power Management Event signal (PME#), are floated and all input signals are ignored. The PME# context is preserved, depending on power management settings. Most of the internal state of the 82546GB is reset on the de-assertion (rising edge) of RST#. |
| LAN_PWR_GOOD | I | Power Good (Power-on Reset). The Power Good signal is used to indicate that stable power is available for the 82546GB. When the signal is low, the 82546GB holds itself in reset state and floats all PCI signals. |

3.2.5 Error Reporting Signals

| Symbol | Type | Name and Function |
|--------|------|---|
| SERR# | OD | System Error. The System Error signal is used by the 82546GB controller to report address parity errors. SERR# is open drain and is actively driven for a single PCI clock when reporting the error. |
| PERR# | STS | Parity Error. The Parity Error signal is used by the 82546GB controller to report data parity errors during all PCI transactions except by a Special Cycle. PERR# is sustained tri-state and must be driven active by the 82546GB controller two data clocks after a data parity error is detected. The minimum duration of PERR# is one clock for each data phase a data parity error is present. |

3.2.6 Power Management Signals

| Symbol | Type | Name and Function |
|---------|------|--|
| PME# | OD | Power Management Event. The 82546GB device drives this signal low when it receives a wake-up event and either the PME Enable bit in the Power Management Control/Status Register or the Advanced Power Management Enable (APME) bit of the Wake-up Control Register (WUC) is 1b. |
| AUX_PWR | I | Auxiliary Power. If the Auxiliary Power signal is high, then auxiliary power is available and the 82546GB device should support the D3cold power state. Note that AUX_PWR is not a supply input, but is an indication of whether AUX_PWR is available to the 82546GB and/or subsystem. Setting AUX_PWR to 1b enables advertising D3cold Wake Up support and changes the reset function of PME_En and PME_Status. AUX_PWR is level sensitive, and any changes are immediately reflected in the D3cold Wake Up advertisements and the PME_En and PME_Status behavior on PCI reset. |



3.2.7 Impedance Compensation Signals

| Symbol | Type | Name and Function |
|---------|------|--|
| ZN_COMP | I/O | <p>N Device Impedance Compensation. This signal should be connected to an external precision resistor (to VDD) that is indicative of the PCI/PCI-X trace load. This cell is used to dynamically determine the drive strength required on the N-channel transistors in the PCI/PCI-X I/O cells.</p> <p>The internal pull-up impedance is nominally 120 KΩ with a minimum of 90 KΩ and a maximum of 190 KΩ.</p> |
| ZP_COMP | I/O | <p>P Device Impedance Compensation. This signal should be connected to an external precision resistor (to VSS) that is indicative of the PCI/PCI-X trace load. This cell is used to dynamically determine the drive strength required on the P-channel transistors in the PCI/PCI-X I/O cells.</p> <p>The internal pull-up impedance is nominally 120 KΩ with a minimum of 90 KΩ and a maximum of 190 KΩ.</p> |

3.2.8 SMB Signals

Note: A pull-up resistor with a recommended value of 4.7 K Ω should be placed along the SMB. A precise value may be calculated from the SMB specification.

| Symbol | Type | Name and Function |
|-----------|------|--|
| SMBCLK | I/O | SMB Clock. The SMB Clock signal is an open drain signal for serial SMB interface. |
| SMBDATA | I/O | SMB Data. The SMB Data signal is an open drain signal for serial SMB interface. |
| SMBALRT # | O | SMB Alert. The SMB Alert signal is open drain for serial SMB interface. |

3.3 EEPROM Interface Signals

| Symbol | Type | Name and Function |
|--------|------|--|
| EE_DI | O | EEPROM Data Input. The EEPROM Data Input pin is used for output to the memory device. |
| EE_DO | I | EEPROM Data Output. The EEPROM Data Output pin is used for input from the memory device. The EE_DO includes an internal pull-up resistor. |
| EE_CS | O | EEPROM Chip Select. The EEPROM Chip Select signal is used to enable the device. |
| EE_SK | O | EEPROM Serial Clock. The EEPROM Shift Clock provides the clock rate for the EEPROM interface, which is approximately 1 MHz. |

3.4 Flash Interface Signals

| Symbol | Type | Name and Function |
|-----------------------------------|------|--|
| FL_ADDR [18:0] | O | Flash Address Output. The Flash Address Output signals are used for a Flash or Boot ROM device. |
| FL_CS# | O | Flash Chip Select. The Flash Chip Select signal is used to enable the Flash or Boot ROM device. |
| FL_OE# | O | Flash Output Enable. The Flash Output Enable signal is used to enable the Flash buffers. |
| FL_WE# | O | Flash Write Enable Output. The Flash Write ENable Output signals are used for write cycles. |
| FL_DATA [7:2] | TS | Flash Data I/O. The Flash Data I/O signals are bi-directional and used for Flash data. These signals include internal pull-up devices. |
| FL_DATA [1:0] LAN_DISA BLE# | TS | Flash Data I/O [1:0] / LAN Port Disable. These pins are inputs from the Flash memory. Alternatively, they can be used to disable the LAN A or LAN B port from a system Super I/O General (GP) port. (FL_DATA[1] corresponds to LAN B, and FL_DATA[0], to LAN A.) They have internal pull-up devices. If the 82546GB is not using Flash functionality, these pins should be connected to external pull-up resistors. If the pins are used as LAN_DISABLE#, the device transitions to a low power state, and the corresponding LAN port is disabled when its pin is sampled low on the rising edge of PCI reset. |

3.5 Miscellaneous Signals

3.5.1 LED Signals

| Symbol | Type | Name and Function |
|----------------|------|---|
| LED1/ACT# | O | Activity. Programmable LED indication. Defaults to flash to indicate transmit or receive activity. |
| LED0/LINK# | O | Link. Programmable LED indication. Defaults to indicate link connectivity. |
| LED2/LINK100# | O | Link100. Programmable LED indication. Defaults to indicate link at 100 Mbps. |
| LED3/LINK1000# | O | Link1000. Programmable LED indication. Defaults to indicate link at 1000 Mbps. |

3.5.2 Software Definable Signals

| Symbol | Type | Name and Function |
|----------------------|------|---|
| SDP[7:6] SDP[1:0] | TS | Software Defined Pin. The Software Defined Pins are reserved and programmable with respect to input and output capability. These default to input signals upon power-up but may be configured differently by the EEPROM. The upper four bits may be mapped to the General Purpose Interrupt bits if they are configured as input signals. Note: SDP5 is not included in the group of Software Defined Pins. |



3.6 PHY Signals

3.6.1 Crystal Signals

| Symbol | Type | Name and Function |
|--------|------|--|
| XTAL1 | I | Crystal One. The Crystal One pin is a 25 MHz +/- 30 ppm input signal. It can be connected to either an oscillator or crystal. If a crystal is used, Crystal Two (XTAL2) must also be connected. |
| XTAL2 | O | Crystal Two. Crystal Two is the output of an internal oscillator circuit used to drive a crystal into oscillation. If an external oscillator is used in the design, XTAL2 must be disconnected. |

3.6.2 PHY Analog Signals

| Symbol | Type | Name and Function |
|------------|------|--|
| REF_A | P | Reference A. This Reference signal should be connected to VSS through an external 2.49 K Ω resistor. |
| MDIA[0]+/- | A | Media Dependent Interface A [0]. 100BASE-T: In MDI configuration, MDIA[0]+/- corresponds to BI_DA+/-, and in MDI-X configuration, MDIA[0]+/- corresponds to BI_DB+/-. 100BASE-TX: In MDI configuration, MDIA[0]+/- is used for the transmit pair, and in MDI-X configuration, MDIA[0]+/- is used for the receive pair. 10BASE-T: In MDI configuration, MDIA[0]+/- is used for the transmit pair, and in MDI-X configuration, MDIA[0]+/- is used for the receive pair. |
| MDIA[1]+/- | A | Media Dependent Interface A [1]. 100BASE-T: In MDI configuration, MDIA[1]+/- corresponds to BI_DB+/-, and in MDI-X configuration, MDIA[1]+/- corresponds to BI_DA+/-. 100BASE-TX: In MDI configuration, MDIA[1]+/- is used for the receive pair, and in MDI-X configuration, MDIA[1]+/- is used for the transmit pair. 10BASE-T: In MDI configuration, MDIA[1]+/- is used for the receive pair, and in MDI-X configuration, MDIA[1]+/- is used for the transmit pair. |
| MDIA[2]+/- | A | Media Dependent Interface A [2]. 100BASE-T: In MDI configuration, MDIA[2]+/- corresponds to BI_DC+/-, and in MDI-X configuration, MDIA[2]+/- corresponds to BI_DD+/-. 100BASE-TX: Unused. 10BASE-T: Unused. |
| MDIA[3]+/- | A | Media Dependent Interface A [3]. 100BASE-T: In MDI configuration, MDIA[3]+/- corresponds to BI_DD+/-, and in MDI-X configuration, MDIA[3]+/- corresponds to BI_DC+/-. 100BASE-TX: Unused. 10BASE-T: Unused. |
| REF_B | P | Reference B. This Reference signal should be connected to VSS through an external 2.49 K Ω resistor. |

| Symbol | Type | Name and Function |
|------------|------|---|
| MDIB[0]+/- | A | Media Dependent Interface B [0]. 1000BASE-T: In MDI configuration, MDIB[0]+/- corresponds to BI_DA+/-, and in MDI-X configuration, MDIB[0]+/- corresponds to BI_DB+/-. 100BASE-TX: In MDI configuration, MDIB[0]+/- is used for the transmit pair, and in MDI-X configuration, MDIB[0]+/- is used for the receive pair. 10BASE-T: In MDI configuration, MDIB[0]+/- is used for the transmit pair, and in MDI-X configuration, MDIB[0]+/- is used for the receive pair. |
| MDIB[1]+/- | A | Media Dependent Interface B [1]. 1000BASE-T: In MDI configuration, MDIB[1]+/- corresponds to BI_DB+/-, and in MDI-X configuration, MDIB[1]+/- corresponds to BI_DA+/-. 100BASE-TX: In MDI configuration, MDIB[1]+/- is used for the receive pair, and in MDI-X configuration, MDIB[1]+/- is used for the transmit pair. 10BASE-T: In MDI configuration, MDIB[1]+/- is used for the receive pair, and in MDI-X configuration, MDIB[1]+/- is used for the transmit pair. |
| MDIB[2]+/- | A | Media Dependent Interface B [2]. 1000BASE-T: In MDI configuration, MDIB[2]+/- corresponds to BI_DC+/-, and in MDI-X configuration, MDIB[2]+/- corresponds to BI_DD+/-. 100BASE-TX: Unused. 10BASE-T: Unused. |
| MDIB[3]+/- | A | Media Dependent Interface B [3]. 1000BASE-T: In MDI configuration, MDIB[3]+/- corresponds to BI_DD+/-, and in MDI-X configuration, MDIB[3]+/- corresponds to BI_DC+/-. 100BASE-TX: Unused. 10BASE-T: Unused. |

3.7 Serializer / Deserializer Signals

| Symbol | Type | Name and Function |
|-----------------------------|------|--|
| RXA+/- RXB +/- | I | SERDES Receive Pairs A and B. These signals make the differential receive pair for the 1.25 GHz serial interface. If the SERDES interface is not used, these pins should not be connected. |
| TXA+/- TXB +/- | O | SERDES Transmit Pairs A and B. These signals make the differential transmit pair for the 1.25 GHz serial interface. If the SERDES interface is not used, these pins should not be connected. |
| SIG_ DETECT (A and B) | I | Signal Detects A and B. These pins indicate whether the SERDES signals (connected to the 1.25 GHz serial interface) have been detected by the optical transceivers. If the SERDES interface is not used, the SIG_DETECT inputs should be connected to ground using pull-down resistors. |



3.8 JTAG Test Interface Signals

| Symbol | Type | Name and Function |
|------------|------|---|
| JTAG_TCK | I | JTAG Clock. |
| JTAG_TDI | I | JTAG TDI. |
| JTAG_TDO | O | JTAG TDO. |
| JTAG_TMS | I | JTAG TMS. |
| JTAG_TRST# | I | JTAG Reset. This is an active low reset signal for JTAG. This signal should be terminated using a pull-down resistor to ground. It must not be left unconnected. |
| CLK_VIEW | O | Clock View. The Clock View signal is an output of clock signals required for IEEE testing. |
| TEST# | I | Factory Test Pin. This is an active low input and has an internal pull-up resistor. For normal operation, TEST# should be left unconnected. |

3.9 Power Supply Connections

3.9.1 Power Support Signals

| Symbol | Type | Name and Function |
|----------|------|---|
| CTRL_15 | O | 1.5 V Control. The 1.5 V Control signal is an output to an external power transistor. If regulators are used, it should be left unconnected. |
| CTRL_25A | O | 2.5 V Control. The 2.5 V Control signal is an output to an external power transistor. If regulators are used, it should be left unconnected. |
| CTRL_25B | O | 2.5 V Control. The 2.5 V Control signal is an output to an external power transistor. If regulators are used, it should be left unconnected. |

3.9.2 Digital Supplies

| Symbol | Type | Name and Function |
|--------|------|---|
| VDDO | P | 3.3 V I/O Power Supply. |
| DVDD | P | 1.5 V Digital Core Power Supply. |

3.9.3 Analog Supplies

| Symbol | Type | Name and Function |
|---------|------|---|
| AVDDH | P | 3.3 V Analog Power Supply. |
| AVDDL A | P | 2.5 V Analog Power Supply to Port A. |
| AVDDL B | P | 2.5 V Analog Power Supply to Port B. |



3.9.4 Ground and No Connects

| Symbol | Type | Name and Function |
|----------|------|--|
| GND | P | Ground. |
| NC | P | No Connect. Do not connect any circuitry to these pins. Pull-up or pull-down resistors should not be connected to these pins. |
| Reserved | R | Reserved. These pins are reserved for factory purposes and should be left unconnected. (However, the following pins should be pulled down to ground: A20, B18, and M5. In addition, the following pins should be pulled down to ground through a 1 K Ω pull-down resistor: A6, E7 and R1.) |

4.0 Test Port Functionality

4.1 XOR Testing

A common board or system-level manufacturing test for proper electrical continuity between a silicon component and the board is some type of cascaded-XOR or NAND tree test. The 82546GB implements an XOR tree spanning most I/O signals. The component XOR tree consists of a series of cascaded XOR logic gates, each stage feeding in the electrical value from a unique pin. The output of the final stage of the tree is visible on an output pin from the component.

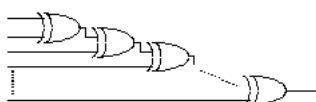


Figure 2. XOR Tree Concept

By connecting to a set of test-points or bed-of-nails fixture, a manufacturing test fixture can test connectivity to each of the component pins included in the tree by sequentially testing each pin, testing each pin when driven both high and low, and observing the output of the tree for the expected signal value and/or change.

4.1.1 XOR Tree Control and Operation

The following signals are required to place the 82546GB in XOR tree test mode:

| Test Function/ Mode | Pin Name | TEST_DM_N | EWRAP | CLK_BYP_N | CLK_VIEW | SDP_B[7] |
|---------------------|----------------|-----------|--------------|--------------|--------------|--------------|
| | Dual-Mode Name | | TEST_MODE[3] | TEST_MODE[2] | TEST_MODE[1] | TEST_MODE[0] |
| XOR Tree Test | | 0 | 0 | 0 | 0 | 0 |



I/O pins with dual-mode function for XOR test:

| Pin Name | Dual-Mode Name | Pin Function |
|-----------|----------------|---------------------|
| FLSH_CE_N | XOR_OUT | Output of XOR tree. |

When XOR tree test is selected, the following pin behavior(s) occur:

- Output drivers for the pins listed as tested are all placed in high-impedance (tri-state) state to ensure that the board/system test fixture can drive the tested inputs without contention
- The output driver for the XOR tree output on pin FLSH_CE_N is explicitly enabled.

4.1.2 Pins Tested

When performing XOR test, those pins tested by the XOR tree all function as inputs, regardless of the normal directionality of the pin. The following table(s) cites the pins tested and not-testable as inputs to the XOR tree. Table entries do not reflect the natural order of input into the XOR tree itself (nor need to, as the output of a multi-input XOR function is order-independent).

Pins included in XOR test tree are listed in [Table 1](#):

Table 1. Tested Pins Included in XOR Tree

| Pin Name | Pin Name | Pin Name |
|----------------|------------------|-----------------|
| PCI_AD[63:0] | M66EN | RX_DATA[7:0] |
| PCI_CBE_N[7:0] | PCI_RST_N | RBC0/RX_CLK |
| PCI_PAR | LAN_PWR_GOOD | RBC1/MTX_CLK |
| PCI_PAR64 | PCI_SERR_N | EE_DI |
| PCI_FRAME_N | PCI_PERR_N | EE_DO |
| PCI_IRDY_N | PCI_PME_N | EE_CS |
| PCI_TRDY_N | AUX_PWR | EE_SK |
| PCI_STOP_N | SMBCLK | FLSH_ADDR[18:0] |
| PCI_IDSEL | SMBDAT | FLSH_OE_N |
| PCI_DEVSEL_N | TX_DATA[9]/TX_ER | FLSH_WE_N |
| PCI_REQ64_N | TX_DATA[8]/TX_EN | FLSH_DATA[7:0] |
| PCI_ACK64_N | TX_DATA[7:0] | LED_A[3:0] |
| PCI_REQ_N | GTX_CLK | LED_B[3:0] |
| PCI_GNT_N | COL | SDP_A[7,6,1,0] |
| PCI_LOCK_N | CRS | SDP_B[6,1,0] |
| PCI_INTA_N | LINK/LOS | ALTCLK_125 |
| PCI_INTB_N | RX_DATA[9]/RX_ER | |
| PCI_CLK | RX_DATA[8]/RX_DV | |



Pins not included in XOR test tree:

- JTAG (TAP) interface: TRST_N, TCK, TDO, TMS, and TDO
- Test mode decode controls TEST_DM_N, EWRAP, CLK_BYP_N, CLK_VIEW, and SDP_B[7]
- Each internal PHY's analog signals including PHYREF, MDI +/-, and PHY_HSDACP/N
- PCI Impedance Compensation ZPCOMP and ZNCOMP
- Oscillator signals XTAL1 and XTAL2
- Test signals including PHY_TSTPT and each PHY's HSDACP/N
- Power-control pins CTRL_15, CTRL_25_A, and CTRL_25_B
- SMB_ALERT_N/PCI_PWR_GOOD

4.2 Tristate Mode

The 82546GB's tristate test mode is used to explicitly disable output drivers and place outputs in high-impedance (tristate) state. To more readily support XOR or NAND-tree like testing of other system components, the 82546GB decodes this test mode from the same signal pins used to exercise XOR tree testing. The 82546GB additionally supports a mechanism to enter tristate mode via the IEEE 802.3 JTAG (TAP) controller.

4.2.1 Tristate Mode Control and Operation

The following signals are required to place the 82546GB in tristate test mode:

| Test Function/ Mode | Pin Name | TEST_DM_N | EWRAP | CLK_BYP_N | CLK_VIEW | SDP_B[7] |
|---------------------|----------------|-----------|--------------|--------------|--------------|--------------|
| | Dual-Mode Name | | TEST_MODE[3] | TEST_MODE[2] | TEST_MODE[1] | TEST_MODE[0] |
| Tristate Mode | | 0 | 0 | 1 | 0 | 1 |

When in tristate test mode:

- All output drivers for all digital signal pins are disabled (with the exception of the TDO pin).
- Analog signals such as MDI+/-, analog test points, and regulator controls are unaffected.

4.2.2 Tristate Mode Using JTAG (TAP)

The 82546GB can also be placed in tristate mode using the JTAG interface and the HIGHZ instruction.

The HIGHZ instruction is used to place the 82546GB in high-impedance (TRISTATE) mode, where all digital signal outputs are placed in high-impedance (tri-state) output state.



5.0 Voltage, Temperature, and Timing Specifications

Note: The specification values listed in this section are subject to change without notice. Verify with your local Intel sales office that you have the latest information before finalizing a design.

5.1 Targeted Absolute Maximum Ratings

Table 2. Absolute Maximum Ratings^a

| Symbol | Parameter | Min | Max | Unit |
|-----------|--|-----------|-------------------------------------|------|
| VDD (3.3) | DC supply voltage on VDDD or AVDDH with respect to VSS | VSS - 0.5 | 4.6 | V |
| VDD (2.5) | DC supply voltage on AVDDL with respect to VSS | VSS - 0.5 | 4.6 or VDD (2.5) + 0.5 ^b | V |
| VDD (1.5) | DC supply voltage on DVDD with respect to VSS | VSS - 0.5 | 4.6 or VDD (1.5) + 0.5 ^c | V |
| VDD | DC supply voltage | VSS - 0.5 | 4.6 | V |
| VI / VO | LVTTL input voltage | VSS - 0.5 | 4.6 | V |
| VI / VO | 5 V compatible input voltage | VSS - 0.5 | 6.6 | V |
| IO | DC output current (by cell type): IOL = 3 mA IOL = 6 mA IOL = 12 mA | | 10 20 40 | mA |
| TSTG | Storage temperature range | -40 | 125 | C |
| | ESD per MIL-STD-883 Test Method 3015, Specification 2001V Latchup Over/Undershoot: 150 mA, 125 C | | VDD overstress: VDD(3.3)(7.2 V) | V |

a. Maximum ratings are referenced to ground (VSS). Permanent device damage is likely to occur if the ratings in this table are exceeded. These values should not be used as the limits for normal device operations.

b. The maximum value is the lesser value of 4.6 V or VDD(2.5) + 0.5 V. This specification applies to biasing the device to a steady state for an indefinite duration.

c. The maximum value is the lesser value of 4.6 V or VDD(2.5) + 0.5 V.

5.2 Recommended Operating Conditions

Table 3. Recommended Operating Conditions^a

| Symbol | Parameter | Min | Max | Unit |
|-----------|---|------|------|------|
| VDD (3.3) | DC supply voltage on VDDD or AVDDH ^b | 3.0 | 3.6 | V |
| VDD (2.5) | DC supply voltage on AVDDL ^c | 2.38 | 2.62 | V |
| VDD (1.5) | DC supply voltage on DVDD | 1.43 | 1.57 | V |
| VIO | PCI bus voltage reference | 3.0 | 5.25 | V |

**Table 3. Recommended Operating Conditions^a**

| Symbol | Parameter | Min | Max | Unit |
|---------|--|-----|------|------|
| tR / tF | Input rise/fall time (normal input) | 0 | 200 | ns |
| tr/tf | input rise/fall time (Schmitt input) | 0 | 10 | ms |
| TA | Operating temperature range (ambient) ^d | 0 | 55 | C |
| TJ | Junction temperature | | ≤125 | C |

- a. Sustained operation of the device at conditions exceeding these values, even if they are within the absolute maximum rating limits, might result in permanent damage.
- b. It is recommended for VDDO to equal AVDDH (VDDO = AVDDH) during power-up and normal operation.
- c. It is recommended for both VDDO and AVDDH to be of a value greater than AVDDL, with a value greater than DVDD, during power-up (VDDO or AVDDH > AVDDL > DVDD).
- d. A higher operating temperature of up to 70 C can be achieved using an appropriate thermal management device.

5.3 DC Specifications

Table 4. DC Characteristics

| Symbol | Parameter | Min | Typ | Max | Units |
|-----------|------------------------------------|------|-----|------|-------|
| VDD (3.3) | DC supply voltage on VDDO or AVDDH | 3.00 | 3.3 | 3.60 | V |
| VDD (2.5) | DC supply voltage on AVDDL | 2.38 | 2.5 | 2.62 | V |
| VDD (1.5) | DC supply voltage on DVDD | 1.43 | 1.5 | 1.57 | V |

Table 5.a Power Supply Characteristics

| | D0a (both ports) | | | | | | | |
|--------------------|-------------------|--------------|-------------------|--------------|--------------------|--------------|---------------------|--------------|
| | Unplugged/No Link | | 10 Mbps Operation | | 100 Mbps Operation | | 1000 Mbps Operation | |
| | Typ Icc (mA) | Max Icc (mA) | Typ Icc (mA) | Max Icc (mA) | Typ Icc (mA) | Max Icc (mA) | Typ Icc (mA) | Max Icc (mA) |
| 3.3 V | 65 | 85 | 100 | 110 | 115 | 120 | 240 | 265 |
| 2.5 V | 60 | 65 | 80 | 80 | 130 | 135 | 310 | 335 |
| 1.5 V | 180 | 190 | 160 | 170 | 200 | 220 | 740 | 840 |
| Total Device Power | 650 mW | | 800 mW | | 1.0 W | | 2.7 W | 3.2 W |



Table 5.b 82546GB Dual Port Ethernet Controller Only

| | D3cold - Wake Up Enabled (both ports) | | | | | | D3cold - Wake Up Disabled (both ports) | |
|--------------------|---------------------------------------|--------------|-------------------|--------------|--------------------|--------------|--|--------------|
| | Unplugged/No Link | | 10 Mbps Operation | | 100 Mbps Operation | | | |
| | Typ lcc (mA) | Max lcc (mA) | Typ lcc (mA) | Max lcc (mA) | Typ lcc (mA) | Max lcc (mA) | Typ lcc (mA) | Max lcc (mA) |
| 3.3 V | 65 | 75 | 100 | 110 | 95 | 120 | 65 | 75 |
| 2.5 V | 65 | 70 | 65 | 70 | 125 | 140 | 60 | 65 |
| 1.5 V | 50 | 50 | 60 | 70 | 105 | 130 | 20 | 40 |
| Total Device Power | 450 mW | | 600 mW | | 800 mW | | 400 mW | |

Table 5.c 82546GB Dual Port Ethernet Controller Only

| | Uninitialized/Disabled | | | |
|--------------------|---------------------------------------|--------------|------------------------------|--------------|
| | D(n) Uninitialized (LAN PWR GOOD = 0) | | Disabled (via Flash Address) | |
| | Typ lcc (mA) | Max lcc (mA) | Typ lcc (mA) | Max lcc (mA) |
| 3.3 V | 75 | 80 | 50 | 55 |
| 2.5 V | 100 | 120 | 50 | 60 |
| 1.5 V | 360 | 385 | 20 | 25 |
| Total Device Power | 1.0 W | | 325 mW | |

Table 5.d Complete Subsystem (Including the 82546GB)

| | Complete Subsystem (including 82546GB, Magnetics, LED, and Regulator Circuits) | | | | | | | |
|-----------------------|--|--------------|----------------------------------|--------------|-----------------------------------|--------------|-----------------|--------------|
| | D3cold / Wake disabled | | D3cold / Wake enabled at 10 Mbps | | D3cold / Wake enabled at 100 Mbps | | D0 at 1000 Mbps | |
| | Typ lcc (mA) | Max lcc (mA) | Typ lcc (mA) | Max lcc (mA) | Typ lcc (mA) | Max lcc (mA) | Typ lcc (mA) | Max lcc (mA) |
| 3.3 V | 65 | 75 | 110 | 120 | 115 | 140 | 250 | 275 |
| 2.5 V | 60 | 65 | 85 | 90 | 175 | 190 | 500 | 525 |
| 1.5 V | 20 | 40 | 60 | 70 | 105 | 130 | 740 | 840 |
| Subsystem Total Power | mW | mW | mW | mW | mW | mW | mW | mW |



Table 5.e 82546GB SerDes Design

| | 82546GB Only | | | |
|--------------------------|------------------------|-----------------|---|-----------------|
| | D0a (SerDes active) | | D3cold Wake Disabled (SerDes off) | |
| | Typ Icc (mA) | Max Icc (mA) | Typ Icc (mA) | Max Icc (mA) |
| 3.3 V | 110 | 135 | 85 | 95 |
| 2.5 V | 120 | 125 | leakage | leakage |
| 1.5 V | 170 | 240 | 15 | 20 |
| Total Device Power | 900 mW | 1.2 W | 300 mW | 375 mW |

Table 5.f Complete Subsystem (SerDes Design - Includes the 82546GB)

| | Complete Subsystem (SerDes design) Including LED and Regulator Circuits (no optics) | | | |
|-------------------------------|---|-----------------|-------------------------------------|-----------------|
| | D3cold Wake Disabled (auxiliary power) | | D0 SerDes Active (primary power) | |
| | Typ Icc (mA) | Max Icc (mA) | Typ Icc (mA) | Max Icc (mA) |
| 3.3 V | 85 | 95 | 110 | 135 |
| 2.5 | ~0 | ~0 | 120 | 125 |
| 1.5 V | 15 | 20 | 170 | 240 |
| Subsystem 3.3 V Current | | 115 mA | | 500 mA |

Table 6. I/O Characteristics

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|------------|--|-----------|------|-----|----------------|------|
| V_{IL} | Voltage input LOW | | -0.5 | | 0.8 | V |
| V_{IH} | Voltage input HIGH | | 2.0 | | $V_{DD} + 0.3$ | V |
| V_{OL} | Voltage output LOW | | | | 0.4 | V |
| V_{OH} | Voltage output HIGH | | 2.4 | | | V |
| V_{SH} | Schmitt Trigger Hysteresis | | 0.1 | | | V |
| I_{OL}^a | Output current LOW 3mA drivers (TTL3) | V_{OL} | 3 | | | mA |
| | 6mA drivers (TTL6) | V_{OL} | 6 | | | mA |
| | 12mA drivers (TTL12) | V_{OL} | 12 | | | mA |

Table 6. I/O Characteristics

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|------------|-----------------------------------|-------------------------------------|------|---------|------|------------|
| I_{OH}^a | Output current HIGH | | | | | |
| | 3mA drivers (TTL3) | V_{OH} | -3 | | | mA |
| | 6mA drivers (TTL6) | V_{OH} | -6 | | | mA |
| | 12mA drivers (TTL12) | V_{OH} | -12 | | | mA |
| I_{IN} | Input Current | | | | | |
| | TTL inputs | $V_{IN} = V_{DD}$ or V_{SS} | -10 | ± 1 | 10 | μA |
| | Inputs with pull-down resistors | $V_{IN} = V_{DD}$ | 150 | | 480 | μA |
| | TTL inputs with pull-up resistors | $V_{IN} = V_{SS}$ | -150 | | -480 | μA |
| I_{OZ} | 3-state output leakage current | $V_{OH} = V_{DD}$ or V_{SS} | -10 | ± 1 | 10 | μA |
| C_{IN} | Input capacitance | Any input and bi-directional buffer | | 2.5 | | pF |
| C_{OUT} | Output capacitance | Any output buffer | | 2.0 | | pF |
| C_{PUD} | Pull-up/down Resistor value | | 7.5 | | 20 | k Ω |

a. TTL3 signals include: EE_DI, EE_SK, EE_CS, and JTAG_TDO.
TTL6 signals include: FL_CE#, CLK_VIEW, FL_DATA[7:0], FL_ADDR[18:0], FL_OE#, and FL_WE#.
TTL12 signals include: ACT_A#, ACT_B#, LINK_A#, LINK_B#, LEDA100#, LEDB100#, LEDA1000#, and LEDB1000#.

5.4 AC Characteristics

Table 7. AC Characteristics: 3.3 V Interfacing

| Symbol | Parameter | Min | Typ | Max | Unit |
|---------|-------------------------------|-----|-----|-----|------|
| fPCICLK | Clock frequency in PCI mode | | | 66 | MHz |
| fPCICLK | Clock frequency in PCI-X mode | 66 | | 133 | MHz |

Table 8. 25 MHz Clock Input Requirements

| Symbol | Parameter ^a | Min | Typ | Max | Unit |
|-----------|------------------------|-------------|-----|-------------|------|
| fi_TX_CLK | TX_CLK_IN frequency | 25 - 50 ppm | 25 | 25 + 50 ppm | MHz |

a. This parameter applies to an oscillator connected to the Crystal One (XTAL1) input. Alternatively, a crystal may be connected to XTAL1 and XTAL2 as the frequency source for the internal oscillator.

Table 9. Link Interface Clock Requirements

| Symbol | Parameter | Min | Typ | Max | Unit |
|-------------------|-------------------|-----|-----|-----|------|
| fGTx ^a | GTx_CLK frequency | | 125 | | MHz |

a. GTx_CLK is used externally for test purposes only.

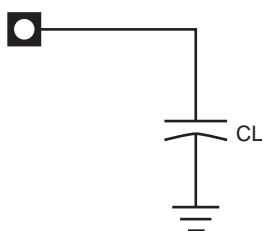
Table 10. EEPROM Interface Clock Requirements

| Symbol | Parameter | Min | Typ | Max | Unit |
|--------|-----------|-----|-----|-----|------|
| fSK | | | | 1 | MHz |

Table 11. AC Test Loads for General Output Pins

| Symbol | Signal Name | Value | Units |
|--------|---|-------|-------|
| CL | TDO | 10 | pF |
| CL | APM_WAKEUP, PME#, SDP[7:6], SDP[1:0] | 16 | pF |
| CL | EE_DI, EE_SK, FL_ADDR[18:0], FL_CS#, FL_OE#, FL_WE#, FL_DATA[7:0] | 18 | pF |
| CL | RX_ACTIVITY, TX_ACTIVITY, LINK_UP | 20 | pF |

Figure 3. AC Test Loads for General Output Pins



5.5 Serial Interface Specifications

Table 12. Driver Characteristics

| Symbol | Parameter | Min | Typ | Max | Units |
|------------------|---|------|-----|------|--------------|
| V_{OD} | Differential Output Voltage Swing ^a | 875 | | 1325 | mV peak-peak |
| V_{OS} | Output Offset Voltage | 1075 | | 1325 | mV |
| ΔV_{OD} | Change in V_{OD} between 0 and 1 ^b | | | 25 | mV |
| R_O | Differential Output Impedance | 80 | | 120 | Ω |
| I_{SA}, I_{SB} | Output Current on Short to VSS | | | 40 | mA |
| I_{SAB} | Output Current when A and B are Shorted | | | 12 | mA |

- a. This is the maximum inside dimension of the eye pattern, measured on high and low data patterns with pre-emphasis present. Load = 100 Ω .
- b. This is defined as an absolute value of amplitude jitter.

Table 13. Receiver Characteristics

| Symbol | Parameter | Min | Typ | Max | Units |
|----------|----------------------------------|-----|-----|------|--------------|
| V_{ID} | Differential Input Voltage Swing | 100 | | 2000 | mV peak-peak |
| R_{IN} | Differential Input Impedance | 80 | | 120 | Ω |

5.6 Timing Specifications

5.6.1 PCI/PCI-X Bus Interface

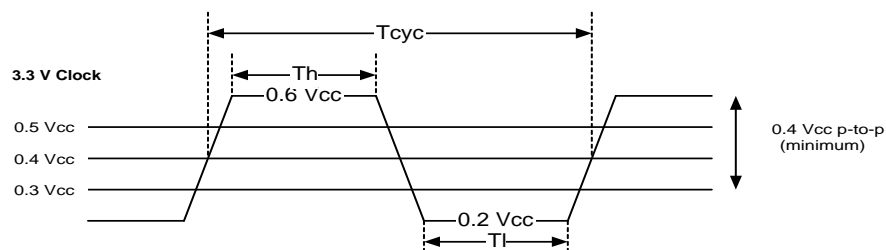
5.6.1.1 PCI/PCI-X Bus Interface Clock

Table 14. PCI/PCI-X Bus Interface Clock Parameters

| Symbol | Parameter ^a | PCI-X 133 MHz | | PCI-X 66 MHz | | PCI 66MHz | | PCI 33 MHz | | Units |
|--------|-----------------------------|---------------|-----|--------------|-----|-----------|-----|------------|-----|-------|
| | | Min | Max | Min | Max | Min | Max | Min | Max | |
| TCYC | CLK cycle time | 7.5 | 20 | 15 | 20 | 15 | 30 | 30 | | ns |
| TH | CLK high time | 3 | | 6 | | 6 | | 11 | | ns |
| TL | CLK low time | 3 | | 6 | | 6 | | 11 | | ns |
| | CLK slew rate | 1.5 | 4 | 1.5 | 4 | 1.5 | 4 | 1 | 4 | V/ns |
| | RST# slew rate ^b | 50 | | 50 | | 50 | | 50 | | mV/ns |

- a. Rise and fall times are specified in terms of the edge rate measured in V/ns. This slew rate must be met across the minimum peak-to-peak portion of the clock waveform as shown.
- b. The minimum RST# slew rate applies only to the rising (de-assertion) edge of the reset signal and ensures that system noise cannot render a monotonic signal to appear bouncing in the switching range.

Figure 4. PCI/PCI-X Clock Timing





5.6.1.2 PCI/PCI-X Bus Interface Timing

Table 15. PCI/PCI-X Bus Interface Timing Parameters

| Symbol | Parameter | PCI-X 133 MHz | | PCI-X 66 MHz | | PCI 66MHz | | PCI 33 MHz | | Units |
|------------|---|---------------|-----|--------------|-----|-----------|-----|------------|-----|-------|
| | | Min | Max | Min | Max | Min | Max | Min | Max | |
| TVAL | CLK to signal valid delay: bussted signals | 0.7 | 3.8 | 0.7 | 3.8 | 2 | 6 | 2 | 11 | ns |
| TVAL (ptp) | CLK to signal valid delay: point-to-point signals | 0.7 | 3.8 | 0.7 | 3.8 | 2 | 6 | 2 | 12 | ns |
| TON | Float to active delay | 0 | | 0 | | 2 | | 2 | | ns |
| TOFF | Active to float delay | | 7 | | 7 | | 14 | | 28 | ns |
| TSU | Input setup time to CLK: bussted signals | 1.2 | | 1.7 | | 3 | | 7 | | ns |
| TSU (ptp) | Input setup time to CLK: point-to-point signals | 1.2 | | 1.7 | | 5 | | 10, 12 | | ns |
| TH | Input hold time from CLK | 0.5 | | 0.5 | | 0 | | 0 | | ns |
| TRRSU | REQ64# to RST# setup time | 10* TCYC | | 10* TCYC | | 10* TCYC | | 10* TCYC | | ns |
| TRRH | RST# to REQ64# hold time | 0 | | 0 | | 0 | | 0 | | ns |

NOTES:

1. Output timing measurements are as shown.
2. REQ# and GNT# signals are point-to-point and have different output valid delay and input setup times than bussted signals. GNT# has a setup of 10 ns; REQ# has a setup of 12 ns. All other signals are bussted.
3. Input timing measurements are as shown.

Table 13. PCI Bus Interface Timing Measurement Conditions

| Symbol | Parameter | PCI-X | PCI 66 MHz 3.3 v | Unit |
|--------|---------------------------------------|----------|---------------------|------|
| VTH | Input measurement test voltage (high) | 0.6*VCC | 0.6*VCC | V |
| VTL | Input measurement test voltage (low) | 0.25*VCC | 0.2*VCC | V |
| VTEST | Output measurement test voltage | 0.4*VCC | 0.4*VCC | V |
| | Input signal slew rate | 1.5 | 1.5 | V/ns |

Figure 5. PCI Bus Interface Output Timing Measurement

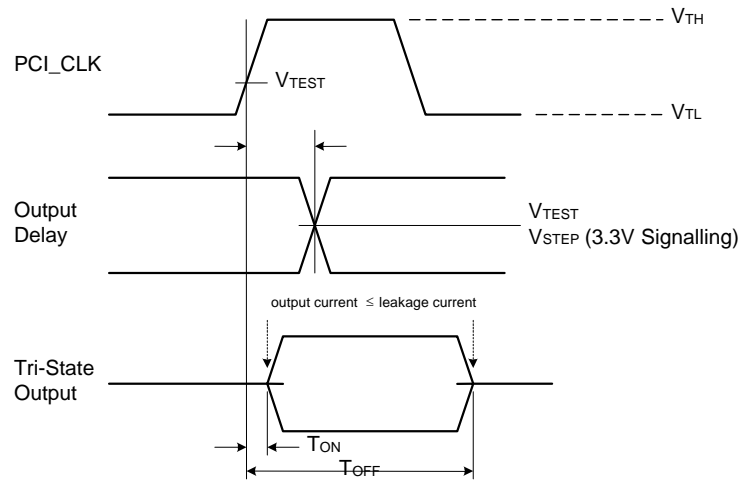


Figure 6. PCI Bus Interface Input Timing Measurement Conditions

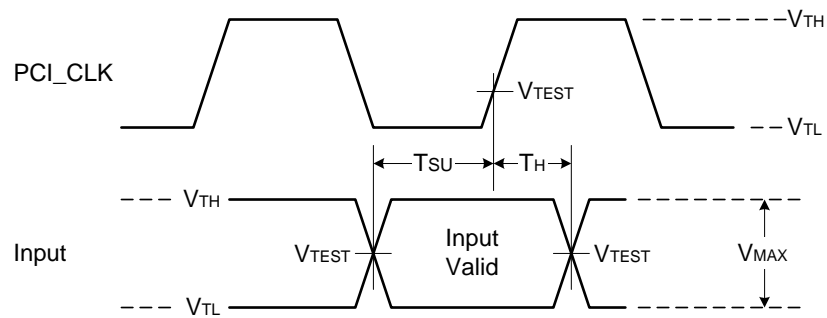


Figure 7. TVAL (max) Rising Edge Test Load

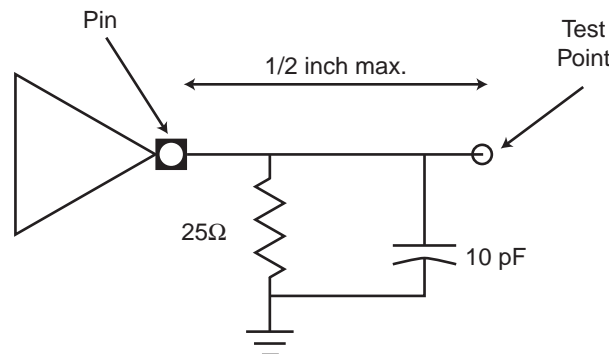
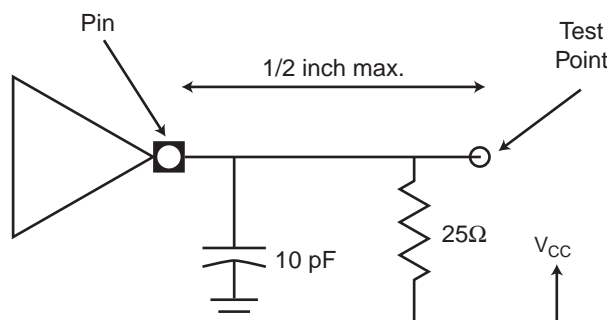


Figure 8. TVAL (max) Falling Edge Test Load



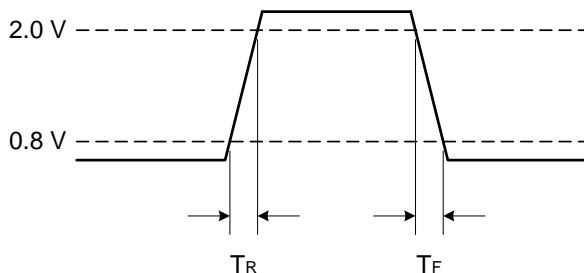
5.6.2 Link Interface Timing

5.6.2.1 Link Interface Rise and Fall Time

Table 16. Rise and Fall Times

| Symbol | Parameter | Condition | Min | Max | Unit |
|--------|-----------------|----------------|-----|-----|------|
| TR | Clock rise time | 0.8 V to 2.0 V | 0.7 | | ns |
| TF | Clock fall time | 2.0 V to 0.8 V | 0.7 | | ns |
| TR | Data rise time | 0.8 to 2.0 V | 0.7 | | ns |
| TF | Data fall time | 2.0 V to 0.8 V | 0.7 | | ns |

Figure 9. Link Interface Rise/Fall Timing



5.6.2.2 Link Interface Transmit Timing

Figure 10. Transmit Interface Timing

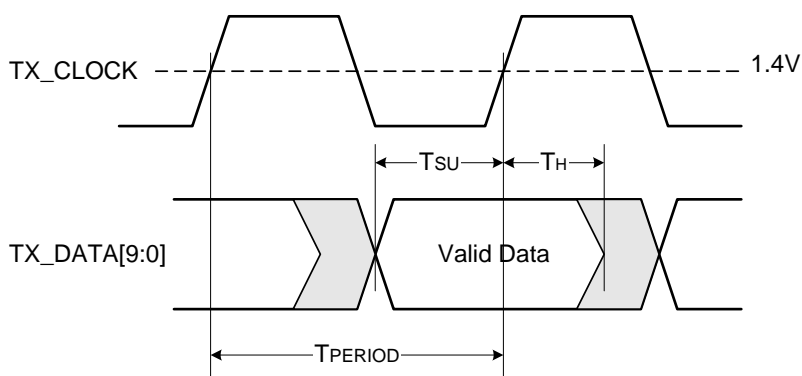


Table 17. Transmit Interface Timing

| Symbol | Parameter | Min | Typ | Max | Unit |
|---------|---|-----|-----|-----|------|
| TPERIOD | GTX_CLK period ^a TBI mode (1000 Mbps) | | 8 | | ns |
| TSETUP | Data setup to rising GTX_CLK | | 2.5 | | ns |
| THOLD | Data hold from rising GRX_CLK | | 1.0 | | ns |
| TDUTY | GTX_CLK duty cycle | 40 | | 60 | % |

a. GTX_CLK should have a 100 ppm tolerance.

5.6.2.3 Link Interface Receive Timing

Figure 11. Receive Interface Timing

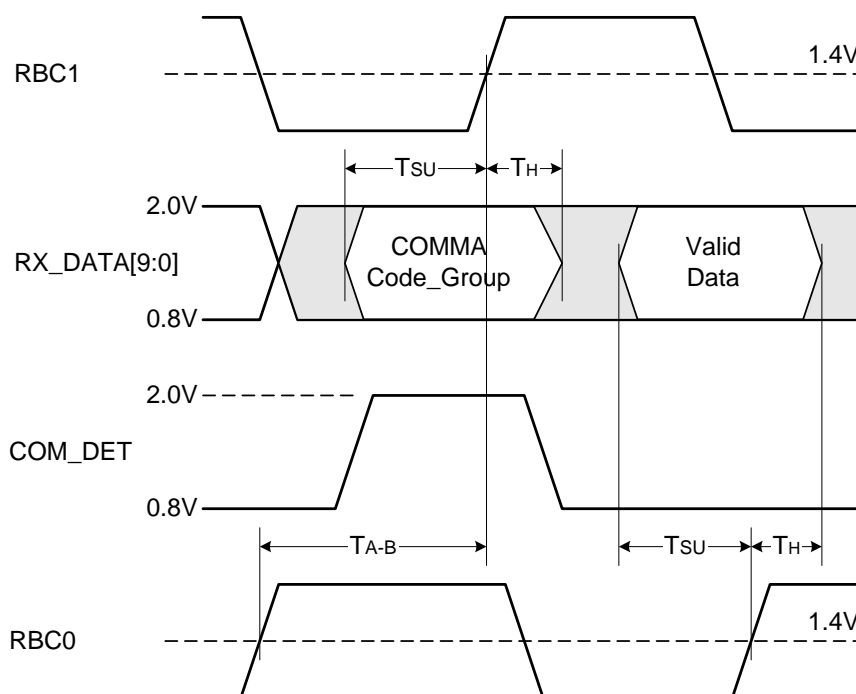


Table 18. Receive Interface Timing

| Symbol | Parameter | Min | Typ | Max | Unit |
|--------|---|-----|------|-----|------|
| TREQ | RBC0/RBC1 frequency TBI mode (1000 Mbps) | | 62.5 | | MHz |
| TSETUP | Data setup before rising RBC0/RBC1 | | 2.5 | | ns |
| THOLD | Data hold after rising RBC0/RBC1 | | 1 | | ns |
| TDUTY | RBC0/RBC1 duty cycle | 40 | | 60 | % |
| TA-B | RBC0/RBC1 skew | 7.5 | | 8.5 | ns |

5.6.3 Flash Interface

Figure 12. Flash Read Timing

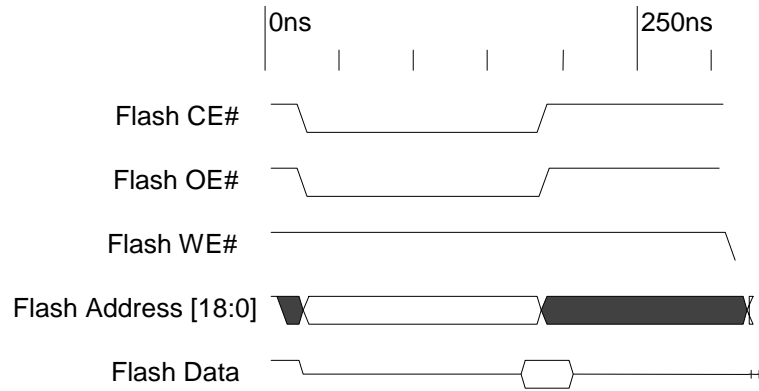
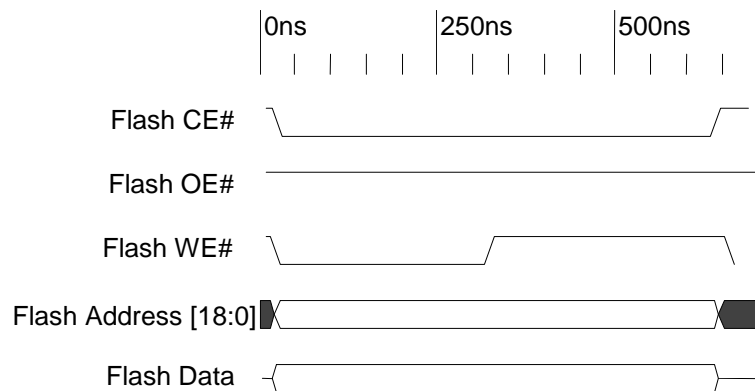


Table 19. Flash Read Operation Timing

| Symbol | Parameter | Min | Typ | Max | Unit |
|--------|-------------------------------------|-----|-----|-----|------|
| TCE | Flash CE# or OE# to read data delay | | | 160 | ns |
| TACC | Flash address setup time | | | 160 | ns |
| THOLD | Data hold time | 0 | | | ns |

Figure 13. Flash Write Timing



**Table 20. Flash Write Operation Timing**

| Symbol | Parameter | Min | Typ | Max | Unit |
|--------|-------------------------------|-----|-----|-----|------|
| TWE | Flash write pulse width (WE#) | | 160 | | ns |
| TAH | Flash address hold time | 0 | | | ns |
| TDS | Flash data setup time | 160 | | | ns |

5.6.4 EEPROM Interface

Table 21. Link Interface Clock Requirements

| Symbol | Parameter | Min | Typ | Max | Unit |
|--------|-------------------|-----|-------------|-----|------|
| TPW | EE_SK pulse width | | TPERIOD*128 | | ns |

Table 22. Link Interface Clock Requirements

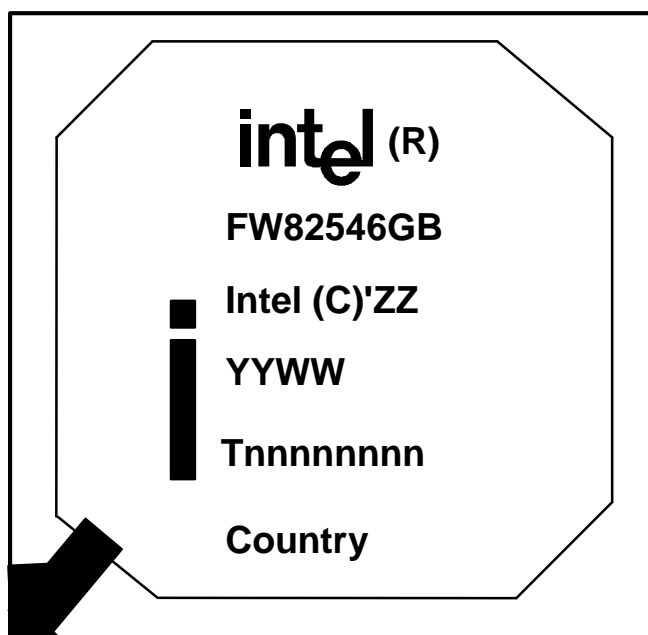
| Symbol | Parameter ^a | Min | Typ | Max | Unit |
|--------|------------------------|--------|-----|-----|------|
| TDOS | EE_DO setup time | TCYC*2 | | | ns |
| TDOH | EE_DO hold time | 0 | | | ns |

a. The EE_DO setup and hold time is a function of the CLK cycle time but is referenced to O_EE_SK.

6.0 Package and Pinout Information

6.1 Device Identification

Figure 14. 82546GB Device Identification Markings



| | |
|-----------|----------------------------|
| 82546GB | Product Name |
| FW82546GB | Intel Product Number |
| (c)'ZZ | Copyright Information |
| YYWW | Date Code |
| Tnnnnnnnn | Lot Trace Code |
| Country | Country of Origin Assembly |

NOTE: The black mark in the lower left corner indicates the location of pin 1.

6.2 Package Information

The 82546GB device is a 364-lead ball grid array (BGA) measuring 21 mm². The package dimensions are detailed in the figures below. The nominal ball pitch is 1 mm.

Figure 15. 82546GB 364-Lead BGA Ball Pad Dimensions

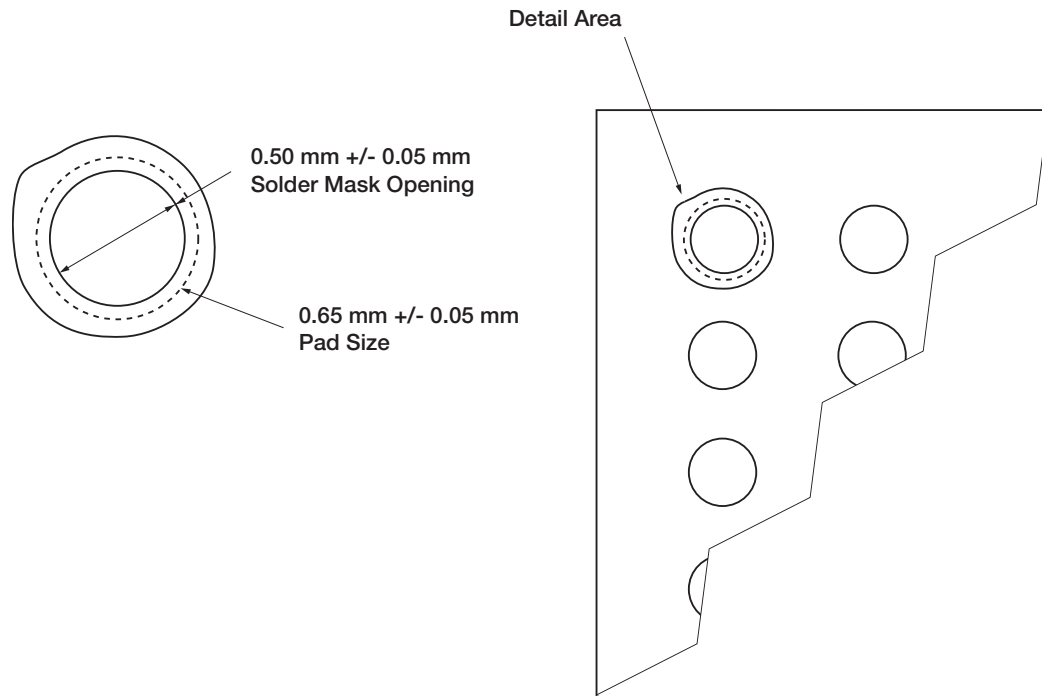


Figure 16. 82546GB Mechanical Specifications

| Symbol | dimension in mm | | | dimension in inch | | |
|--------|-----------------|-------|-------|-------------------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 2.03 | 2.23 | 2.43 | 0.080 | 0.088 | 0.096 |
| A1 | 0.40 | 0.50 | 0.60 | 0.016 | 0.020 | 0.024 |
| A2 | 1.12 | 1.17 | 1.22 | 0.044 | 0.046 | 0.048 |
| b | 0.50 | 0.60 | 0.70 | 0.020 | 0.024 | 0.028 |
| C | 0.51 | 0.56 | 0.61 | 0.020 | 0.022 | 0.024 |
| D | 20.80 | 21.00 | 21.20 | 0.819 | 0.827 | 0.835 |
| D1 | 19.00 BSC | | | 0.748 BSC | | |
| D2 | 18.80 | 19.00 | 19.20 | 0.740 | 0.748 | 0.756 |
| D3 | 15.00 | | | 0.591 | | |
| E | 20.80 | 21.00 | 21.20 | 0.819 | 0.827 | 0.835 |
| E1 | 19.00 BSC | | | 0.748 BSC | | |
| E2 | 18.80 | 19.00 | 19.20 | 0.740 | 0.748 | 0.756 |
| E3 | 15.00 | | | 0.591 | | |
| e | 1.0 BASIC | | | 0.039 BASIC | | |
| aaa | 0.20 | | | 0.008 | | |
| bbb | 0.25 | | | 0.010 | | |
| ddd | 0.15 | | | 0.006 | | |
| eee | 0.25 | | | 0.010 | | |
| fff | 0.10 | | | 0.004 | | |
| θ | 30° TYP | | | 30° TYP | | |

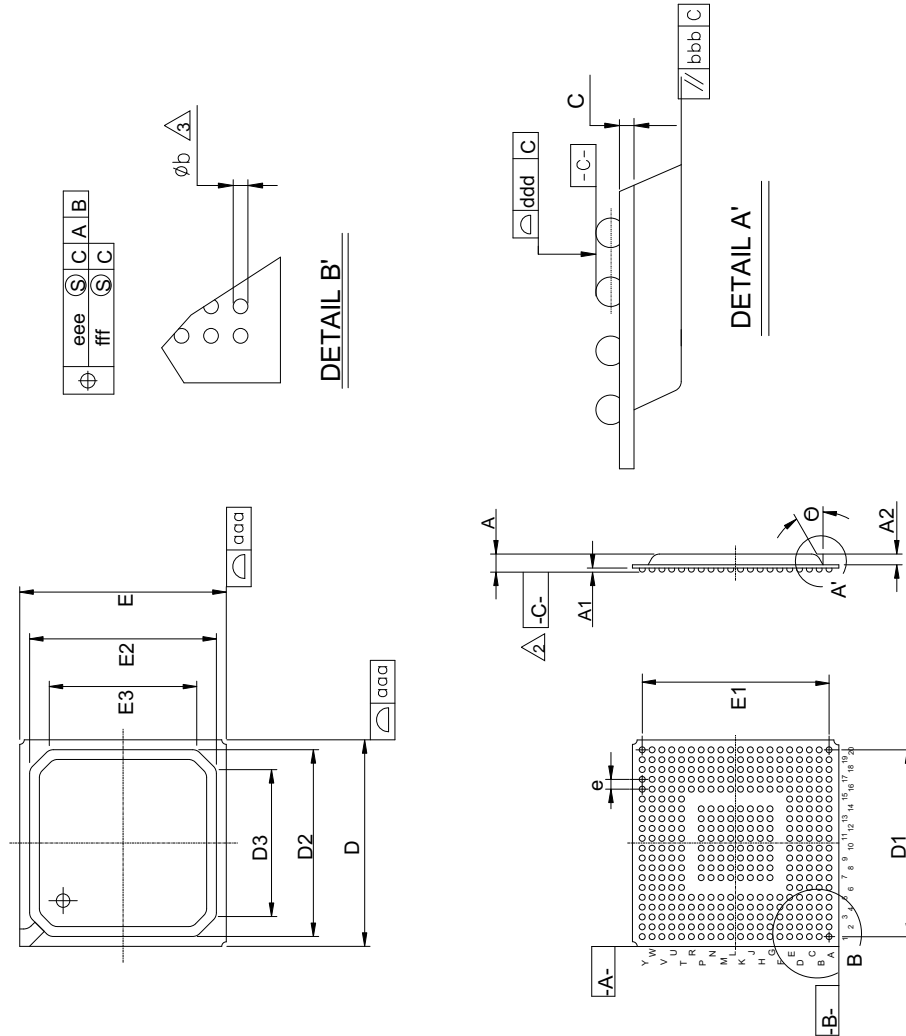
NOTE:

1. CONTROLLING DIMENSION: MILLIMETER.

△ PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

△ DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THERE SHALL BE A MINIMUM CLEARANCE OF 0.25 mm BETWEEN THE EDGE OF THE SOLDER BALL AND THE BODY EDGE.





6.3 Thermal Specifications

The 82546GB Gigabit Ethernet controller is specified for operation when the ambient temperature (TA) is within the range of 0° C to 55° C. The maximum permitted junction temperature is 125° C.

TC (case temperature) is calculated using the equation:

$$TC = TA + P (\theta_{JA} - \theta_{JC})$$

TJ (junction temperature) is calculated using the equation:

$$TJ = TA + P \theta_{JA}$$

The power consumption (P) is calculated by using the typical ICC and nominal VCC. The thermal resistances are shown in [Table 23](#).

Table 23. Thermal Characteristics

| Symbol | Parameter | Value at specified airflow (m/s) | | | | Units |
|---------------|---|----------------------------------|------|------|------|--------|
| | | 0 | 1 | 2 | 3 | |
| θ_{JA} | Thermal resistance, junction-to-ambient | 17.7 | 15.6 | 14.8 | 14.0 | C/Watt |
| θ_{JC} | Thermal resistance, junction-to-case | 6.8 | 6.8 | 6.8 | 6.8 | C/Watt |

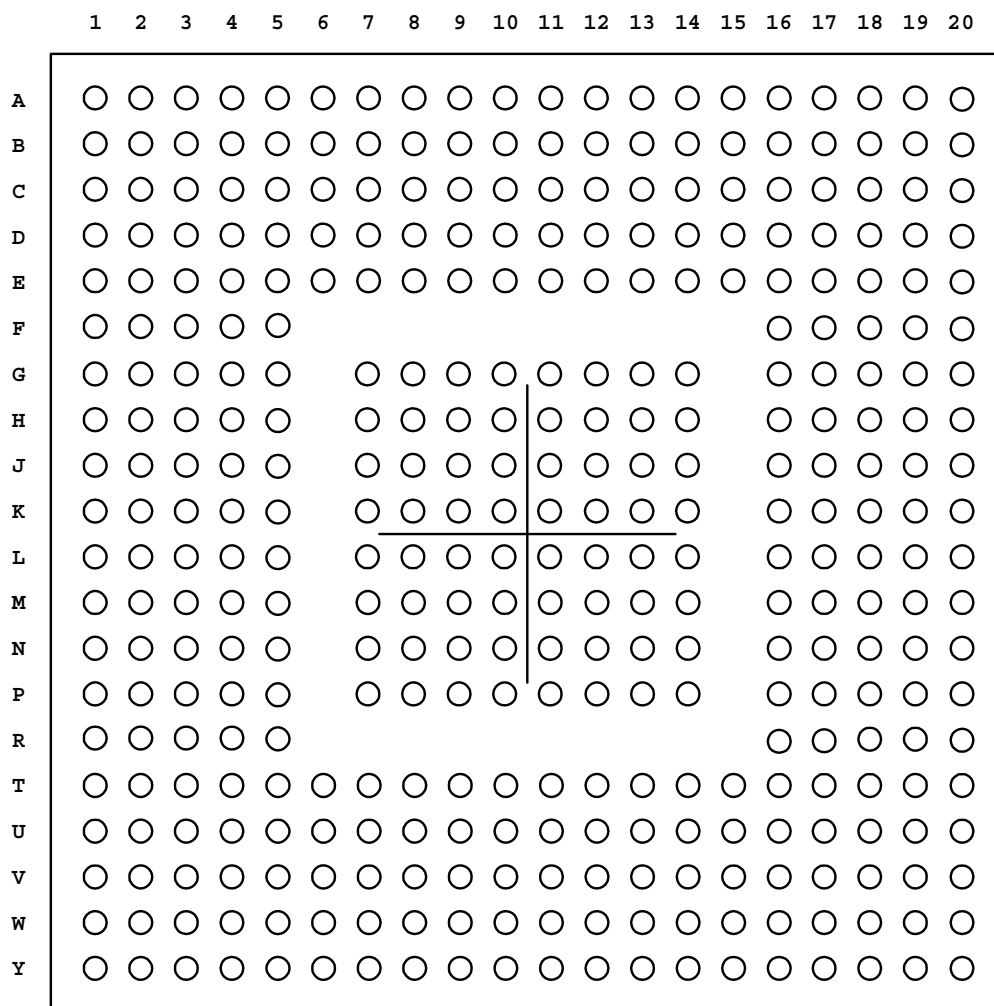
Thermal resistances are determined empirically with test devices mounted on standard thermal test boards. Real system designs may have different characteristics due to board thickness, arrangement of ground planes, and proximity of other components. The case temperature measurements should be used to assure that the 82546GB Gigabit Ethernet controller is operating under recommended conditions.

The use of a heat sink device can enhance the overall θ_{JA} of the solution in situations where tolerance of higher overall ambient air temperatures is desired. Intel does not qualify or recommend any specific heat sink device for use with the 82546GB Gigabit Ethernet controller but can provide a thermal report modeling a generic heat sink device and the θ_{JA} that might be achieved with the use of a heat sink device. Refer to the *82546EB/GB Gigabit Ethernet Controller Thermal Properties with External Heat Sink* Application Note for more information.



6.4 Ball Mapping Diagram

Note: The 82546GB device uses five categories of VDD connections: VDDO (3.3 V), AVDDH (Analog 3.3 V), AVDDL (Analog 2.5 V), and DVDD (1.5 V).





6.5 Pinout Information

Table 24. PCI Address, Data, and Control Signals

| Signal | Pin | Signal | Pin | Signal | Pin |
|------------|-----|------------|-----|------------|-----|
| PCI_AD[0] | T14 | PCI_AD[28] | Y3 | PCI_AD[56] | T17 |
| PCI_AD[1] | V14 | PCI_AD[29] | U4 | PCI_AD[57] | U18 |
| PCI_AD[2] | Y15 | PCI_AD[30] | V3 | PCI_AD[58] | V18 |
| PCI_AD[3] | W14 | PCI_AD[31] | V1 | PCI_AD[59] | U16 |
| PCI_AD[4] | T13 | PCI_AD[32] | L16 | PCI_AD[60] | V17 |
| PCI_AD[5] | V13 | PCI_AD[33] | M20 | PCI_AD[61] | W18 |
| PCI_AD[6] | Y14 | PCI_AD[34] | M19 | PCI_AD[62] | Y19 |
| PCI_AD[7] | U12 | PCI_AD[35] | M16 | PCI_AD[63] | T16 |
| PCI_AD[8] | V12 | PCI_AD[36] | M18 | CBE[0]# | Y13 |
| PCI_AD[9] | T12 | PCI_AD[37] | M17 | CBE[1]# | V10 |
| PCI_AD[10] | W12 | PCI_AD[38] | N20 | CBE[2]# | T8 |
| PCI_AD[11] | Y12 | PCI_AD[39] | N16 | CBE[3]# | Y4 |
| PCI_AD[12] | V11 | PCI_AD[40] | P20 | CBE[4]# | V16 |
| PCI_AD[13] | T11 | PCI_AD[41] | N18 | CBE[5]# | Y18 |
| PCI_AD[14] | Y11 | PCI_AD[42] | P19 | CBE[6]# | Y17 |
| PCI_AD[15] | W10 | PCI_AD[43] | P16 | CBE[7]# | T15 |
| PCI_AD[16] | U8 | PCI_AD[44] | R20 | PAR | U10 |
| PCI_AD[17] | Y7 | PCI_AD[45] | P18 | PAR64 | V15 |
| PCI_AD[18] | Y6 | PCI_AD[46] | P17 | FRAME# | V8 |
| PCI_AD[19] | V7 | PCI_AD[47] | T20 | IRDY# | W8 |
| PCI_AD[20] | T7 | PCI_AD[48] | R16 | TRDY# | Y8 |
| PCI_AD[21] | W6 | PCI_AD[49] | U20 | STOP# | V9 |
| PCI_AD[22] | Y5 | PCI_AD[50] | R18 | IDSEL | T6 |
| PCI_AD[23] | V6 | PCI_AD[51] | T19 | DEVSEL# | T9 |
| PCI_AD[24] | U6 | PCI_AD[52] | V20 | VIO | Y1 |
| PCI_AD[25] | V5 | PCI_AD[53] | T18 | VIO | Y20 |
| PCI_AD[26] | W4 | PCI_AD[54] | W20 | | |
| PCI_AD[27] | V4 | PCI_AD[55] | V19 | | |

Table 25. PCI Arbitration Signals

| Signal | Pin | Signal | Pin | Signal | Pin |
|--------|-----|--------|-----|--------|-----|
| REQ64# | U14 | REQ# | W2 | LOCK# | Y9 |
| ACK64# | W16 | GNT# | T3 | | |

**Table 26. Interrupt Signals**

| Signal | Pin | Signal | Pin |
|--------|-----|--------|-----|
| INTA# | Y2 | INTB# | T1 |

Table 27. System Signals

| Signal | Pin | Signal | Pin |
|--------|-----|--------------|-----|
| PCICLK | U2 | PCIRST# | T5 |
| M66EN | Y16 | LAN_PWR_GOOD | A17 |

Table 28. Error Reporting Signals

| Signal | Pin | Signal | Pin |
|--------|-----|--------|-----|
| SERR# | T10 | PERR# | Y10 |

Table 29. Power Management Signals

| Signal | Pin | Signal | Pin |
|--------|-----|---------|-----|
| PME# | T4 | AUX_PWR | R3 |

Table 30. Impedance Compensation Signals

| Signal | Pin | Signal | Pin |
|---------|-----|---------|-----|
| ZN_COMP | T2 | ZP_COMP | R5 |

Table 31. SMB Signals

| Signal | Pin | Signal | Pin | Signal | Pin |
|--------|-----|---------|-----|----------|-----|
| SMBCLK | A14 | SMBDATA | A15 | SMBALRT# | A16 |

Table 32. EEPROM Interface Signals

| Signal | Pin | Signal | Pin |
|--------|-----|--------|-----|
| EE_DI | C19 | EE_CS | C20 |
| EE_DO | B20 | EE_SK | D20 |

**Table 33. Flash Interface Signals**

| Signal | Pin | Signal | Pin | Signal | Pin |
|------------|-----|-------------|-----|-------------------------------|-----|
| FL_ADDR[0] | F16 | FL_ADDR[10] | G17 | FL_OE# | K18 |
| FL_ADDR[1] | E18 | FL_ADDR[11] | G16 | FL_WE# | C17 |
| FL_ADDR[2] | E16 | FL_ADDR[12] | B15 | FL_DATA[0] / LAN_A_DISABLE | H16 |
| FL_ADDR[3] | E15 | FL_ADDR[13] | D19 | FL_DATA[1] / LAN_B_DISABLE | G18 |
| FL_ADDR[4] | E14 | FL_ADDR[14] | D18 | FL_DATA[2] | J16 |
| FL_ADDR[5] | E13 | FL_ADDR[15] | C15 | FL_DATA[3] | H18 |
| FL_ADDR[6] | D15 | FL_ADDR[16] | D16 | FL_DATA[4] | J17 |
| FL_ADDR[7] | B16 | FL_ADDR[17] | C18 | FL_DATA[5] | J18 |
| FL_ADDR[8] | F17 | FL_ADDR[18] | D17 | FL_DATA[6] | K17 |
| FL_ADDR[9] | F18 | FL_CS# | H20 | FL_DATA[7] | K16 |

Table 34. LED Signals

| Signal | Pin | Signal | Pin | Signal | Pin |
|-----------|-----|------------|-----|------------|-----|
| ACT_A# | N1 | LINKA1000# | N3 | LINKB100# | C14 |
| LINK_A# | M1 | ACT_B# | B13 | LINKB1000# | C13 |
| LINKA100# | N4 | LINK_B# | A13 | | |

Table 35. Software Definable Signals

| Signal | Pin | Signal | Pin |
|---------|-----|---------|-----|
| SDPA[0] | G4 | SDPB[0] | D13 |
| SDPA[1] | G5 | SDPB[1] | B12 |
| SDPA[6] | E12 | SDPB[6] | C12 |
| SDPA[7] | E11 | SDPB[7] | D12 |

Table 36. Crystal Signals

| Signal | Pin | Signal | Pin |
|--------|-----|--------|-----|
| XTAL1 | A3 | XTAL2 | A4 |

Table 37. PHY Signals

| Signal | Pin | Signal | Pin | Signal | Pin |
|--------|-----|--------|-----|--------|-----|
| REF_A | E3 | MDIA2- | D1 | MDIB1- | L1 |
| REF_B | L4 | MDIA2+ | D2 | MDIB1+ | K1 |
| MDIA0- | B1 | MDIA3- | E1 | MDIB2- | J2 |



Table 37. PHY Signals

| Signal | Pin | Signal | Pin | Signal | Pin |
|--------|-----|--------|-----|--------|-----|
| MDIA0+ | B2 | MDIA3+ | E2 | MDIB2+ | J1 |
| MDIA1- | C1 | MDIB0- | L3 | MDIB3- | H3 |
| MDIA1+ | C2 | MDIB0+ | K3 | MDIB3+ | J3 |

Table 38. Serializer / Deserializer Signals

| Signal | Pin | Signal | Pin | Signal | Pin |
|--------|-----|--------|-----|--------------|-----|
| RXA+ | G19 | TXA+ | F19 | SIG_DETECT_A | E20 |
| RXA- | G20 | TXA- | F20 | SIG_DETECT_B | L20 |
| RXB+ | J19 | TXB+ | K19 | | |
| RXB- | J20 | TXB- | K20 | | |

Table 39. JTAG Test Interface Signals

| Signal | Pin | Signal | Pin | Signal | Pin |
|----------|-----|-----------|-----|----------|-----|
| JTAG_TCK | P1 | JTAG_TMS | P5 | CLK_VIEW | P3 |
| JTAG_TDI | P4 | JTAG_RST# | N5 | TEST# | A8 |
| JTAG_TDO | P2 | | | | |

Table 40. Power Support Signals

| Signal | Pin | Signal | Pin | Signal | Pin |
|---------|-----|----------|-----|--------|-----|
| CTRL_15 | A18 | CTRL_25A | F2 | CTRL_B | H5 |

**Table 41. Digital Power Signals**

| Signal | Pin | Signal | Pin | Signal | Pin |
|---------------------|-----|-------------------|-----|-------------|-----|
| VDDO (3.3V) | B8 | VDDO (3.3V) | U7 | DVDD (1.5V) | H13 |
| VDDO (3.3V) | B14 | VDDO (3.3V) - PLL | U11 | DVDD (1.5V) | H14 |
| VDDO (3.3V) | B19 | VDDO (3.3V) | U15 | DVDD (1.5V) | J7 |
| VDDO (3.3V) | C10 | VDDO (3.3V) | U19 | DVDD (1.5V) | J14 |
| VDDO (3.3V) | C16 | VDDO (3.3V) | W1 | DVDD (1.5V) | M7 |
| VDDO (3.3V) | D6 | VDDO (3.3V) | W5 | DVDD (1.5V) | M14 |
| VDDO (3.3V) | D11 | VDDO (3.3V) | W9 | DVDD (1.5V) | N7 |
| VDDO (3.3V) | E17 | VDDO (3.3V) | W13 | DVDD (1.5V) | N8 |
| VDDO (3.3V) - PHY B | H4 | VDDO (3.3V) | W17 | DVDD (1.5V) | N13 |
| VDDO (3.3V) | H19 | DVDD (1.5V) | G7 | DVDD (1.5V) | N14 |
| VDDO (3.3V) | L17 | DVDD (1.5V) | G8 | DVDD (1.5V) | P7 |
| VDDO (3.3V) | M2 | DVDD (1.5V) | G9 | DVDD (1.5V) | P8 |
| VDDO (3.3V) | N19 | DVDD (1.5V) | G12 | DVDD (1.5V) | P9 |
| VDDO (3.3V) | R4 | DVDD (1.5V) | G13 | DVDD (1.5V) | P12 |
| VDDO (3.3V) | R17 | DVDD (1.5V) | G14 | DVDD (1.5V) | P13 |
| VDDO (3.3V) | U1 | DVDD (1.5V) | H7 | DVDD (1.5V) | P14 |
| VDDO (3.3V) | U3 | DVDD (1.5V) | H8 | | |

Table 42. Analog Power Signals

| Signal | Pin | Signal | Pin | Signal | Pin |
|-----------------------|-----|----------------|-----|-----------------|-----|
| AVDDH (3.3 V) | B4 | AVDDLA (2.5 V) | G1 | AVDDL B (2.5 V) | L2 |
| AVDDH (3.3 V) - PHY A | F1 | AVDDLA (2.5 V) | G2 | AVDDL B (2.5 V) | L5 |
| AVDDLA (2.5 V) | A19 | AVDDLA (2.5 V) | G3 | AVDDL B (2.5 V) | L18 |



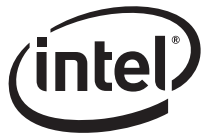
Table 43. Grounds and No Connect Signals

| Signal | Pin | Signal | Pin | Signal | Pin |
|--------|-----|--------|-----|--------|-----|
| GND | A1 | GND | K2 | GND | N10 |
| GND | A2 | GND | K4 | GND | N11 |
| GND | A5 | GND | K5 | GND | N12 |
| GND | A10 | GND | K7 | GND | N17 |
| GND | B3 | GND | K8 | GND | P10 |
| GND | B6 | GND | K9 | GND | P11 |
| GND | B11 | GND | K10 | GND | R2 |
| GND | B17 | GND | K11 | GND | R19 |
| GND | C3 | GND | K12 | GND | U5 |
| GND | D3 | GND | K13 | GND | U9 |
| GND | D8 | GND | K14 | GND | U13 |
| GND | D14 | GND | L7 | GND | U17 |
| GND | E19 | GND | L8 | GND | V2 |
| GND | F3 | GND | L9 | GND | W3 |
| GND | G10 | GND | L10 | GND | W7 |
| GND | G11 | GND | L11 | GND | W11 |
| GND | H2 | GND | L12 | GND | W15 |
| GND | H9 | GND | L13 | GND | W19 |
| GND | H10 | GND | L14 | NC | A11 |
| GND | H11 | GND | L19 | NC | A12 |
| GND | H12 | GND | M4 | NC | F4 |
| GND | H17 | GND | M8 | NC | F5 |
| GND | J8 | GND | M9 | NC | H1 |
| GND | J9 | GND | M10 | NC | J4 |
| GND | J10 | GND | M11 | NC | J5 |
| GND | J11 | GND | M12 | NC | M3 |
| GND | J12 | GND | M13 | NC | N2 |
| GND | J13 | GND | N9 | | |



Table 44. Reserved Signals

| Signal | Pin | Signal | Pin | Signal | Pin |
|-------------|-----|--------------|-----|--------------|-----|
| Reserved[0] | D4 | Reserved[10] | E10 | Reserved[20] | A9 |
| Reserved[1] | D5 | Reserved[11] | B7 | Reserved[21] | C11 |
| Reserved[2] | C4 | Reserved[12] | A7 | Reserved[22] | B10 |
| Reserved[3] | E4 | Reserved[13] | C8 | Reserved[23] | C6 |
| Reserved[4] | C5 | Reserved[14] | E8 | Reserved[24] | A20 |
| Reserved[5] | E5 | Reserved[15] | E9 | Reserved[25] | B18 |
| Reserved[6] | B5 | Reserved[16] | D9 | Reserved[26] | M5 |
| Reserved[7] | E6 | Reserved[17] | C9 | Reserved[27] | E7 |
| Reserved[8] | D7 | Reserved[18] | B9 | Reserved[28] | A6 |
| Reserved[9] | C7 | Reserved[19] | D10 | Reserved[29] | R1 |



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